

CLAIMS

1. A method comprising:
 - A. providing a substrate having a first surface and a second surface, the first surface being adapted for mounting an electronic device thereon, the substrate including a grid of electrically conductive vias extending from a region proximate the first surface to a region proximate the second surface, each via being one of a signal via, a ground via and a power via;
 - B. removing at least one of the vias to form a void between at least one ground via and at least one power via; and
 - C. connecting each of the at least one ground via proximate the void to one of the at least one power vias proximate the void with a filter device proximate the second surface of the substrate.
2. The method of claim 1 wherein the vias removed in Step B are ground vias.
3. The method of claim 1 wherein the filter device comprises a capacitor.
4. The method of claim 1 wherein the vias in the grid are disposed at a first pitch with respect to each other.
5. The method of claim 1 wherein the void comprises a loop around at least one via.

6. A method comprising:
 - A. providing a substrate having a first surface and a second surface, the first surface being adapted for mounting an electronic device thereon;
 - B. forming a grid of electrically conductive vias extending from a region proximate the first surface to a region proximate the second surface, each via being one of a signal via, a ground via and a power via;
 - C. removing at least one of the vias to form a void between at least one ground via and at least one power via; and
 - D. connecting each of the at least one ground via proximate the void to one of the at least one power vias proximate the void with a filter device proximate the second surface of the substrate.
7. The method of claim 6 wherein the vias removed in Step C are ground vias.
8. The method of claim 6 wherein the filter device comprises a capacitor.
9. The method of claim 6 wherein the vias in the grid are disposed at a first pitch with respect to each other.
10. The method of claim 6 wherein the void comprises a loop around at least one via.

11. A method comprising:
- A. providing a substrate having a first surface and a second surface, the first surface being adapted for mounting an electronic device thereon;
 - B. forming a grid including a plurality of electrically conductive vias extending from a region proximate the first surface to a region proximate the second surface and a void between at least one ground via and at least one power via, each via being one of a signal via, a ground via and a power via and the void being an area lacking at least one via; and
 - C. connecting one of the at least one ground vias proximate the void to at least one of the at least one power vias proximate the void with a filter device proximate the second surface of the substrate.
12. The method of claim 11 wherein the vias removed in Step B are ground vias.
13. The method of claim 11 wherein the filter device comprises a capacitor.
14. The method of claim 11 wherein the vias in the grid are disposed at a first pitch with respect to each other.
15. The method of claim 11 wherein the void comprises a loop around at least one via.